

74LCX574

Low Voltage Octal D-Type Flip-Flop with 5V Tolerant Inputs and Outputs

General Description

The LCX574 is a high-speed, low power octal flip-flop with a buffered common Clock (CP) and a buffered common Output Enable (OE). The information presented to the D inputs is stored in the flip-flops on the LOW-to-HIGH Clock (CP) transition.

The LCX574 is functionally identical to the LCX374 except for the pinouts.

The LCX574 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The LCX574 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 7.5 ns t_{PD} max ($V_{CC} = 3.3V$), 10 μA I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V

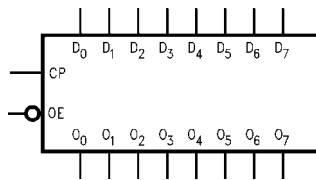
Note 1: To Ensure the high-Impedance state during power up or down, \overline{OE} should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

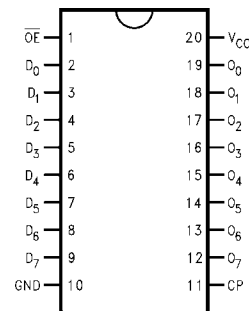
Order Number	Package Number	Package Description
74LCX574WMM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX574SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX574MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LCX574MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description
D_0 – D_7	Data Inputs
CP	Clock Pulse Input
\overline{OE}	3-STATE Output Enable Input
O_0 – O_7	3-STATE Outputs

Functional Description

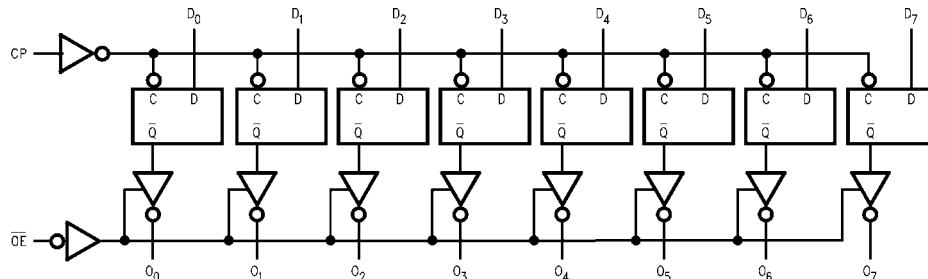
The LCX574 consists of eight edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable (\overline{OE}) LOW, the contents of the eight flip-flops are available at the outputs. When \overline{OE} is HIGH, the outputs go to the high impedance state. Operation of the \overline{OE} input does not affect the state of the flip-flops.

Truth Table

Inputs			Internal	Outputs	Function
\overline{OE}	CP	D	Q	O_n	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	↗	L	L	Z	Load
H	↗	H	H	Z	Load
L	↗	L	L	L	Data Available
L	↗	H	H	H	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = High Impedance
 ↗ = LOW-to-HIGH Transition
 NC = No Change

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 2)						
Symbol	Parameter	Value	Conditions	Units		
V_{CC}	Supply Voltage	-0.5 to +7.0		V		
V_I	DC Input Voltage	-0.5 to +7.0		V		
V_O	DC Output Voltage	-0.5 to +7.0 -0.5 to $V_{CC} + 0.5$	Output in 3-STATE Output in HIGH or LOW State (Note 3)	V		
I_{IK}	DC Input Diode Current	-50	$V_I < GND$	mA		
I_{OK}	DC Output Diode Current	-50 +50	$V_O < GND$ $V_O > V_{CC}$	mA		
I_O	DC Output Source/Sink Current	±50		mA		
I_{CC}	DC Supply Current per Supply Pin	±100		mA		
I_{GND}	DC Ground Current per Ground Pin	±100		mA		
T_{STG}	Storage Temperature	-65 to +150		°C		
Recommended Operating Conditions (Note 4)						
Symbol	Parameter	Min	Max	Units		
V_{CC}	Supply Voltage	Operating	2.0	3.6	V	
		Data Retention	1.5	3.6		
V_I	Input Voltage	0	5.5	V		
V_O	Output Voltage	HIGH or LOW State	0	V_{CC}	V	
		3-STATE	0	5.5		
I_{OH}/I_{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		±24	mA	
		$V_{CC} = 2.7V - 3.0V$		±12		
		$V_{CC} = 2.3V - 2.7V$		±8		
T_A	Free-Air Operating Temperature	-40	85	°C		
$\Delta t/\Delta V$	Input Edge Rate, $V_{IN} = 0.8V - 2.0V$, $V_{CC} = 3.0V$	0	10	ns/V		
<p>Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.</p> <p>Note 3: I_O Absolute Maximum Rating must be observed.</p> <p>Note 4: Unused inputs must be held HIGH or LOW. They may not float.</p>						
DC Electrical Characteristics						
Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40^\circ C \text{ to } +85^\circ C$		Units
				Min	Max	
V_{IH}	HIGH Level Input Voltage		2.3 - 2.7	1.7		V
			2.7 - 3.6	2.0		
V_{IL}	LOW Level Input Voltage		2.3 - 2.7		0.7	V
			2.7 - 3.6		0.8	
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -100 \mu A$	2.3 - 3.6	$V_{CC} - 0.2$		V
		$I_{OH} = -8 \text{ mA}$	2.3	1.8		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2		
		$I_{OH} = -18 \text{ mA}$	3.0	2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.2		
V_{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.3 - 3.6		0.2	V
		$I_{OL} = 8 \text{ mA}$	2.3		0.6	
		$I_{OL} = 12 \text{ mA}$	2.7		0.4	
		$I_{OL} = 16 \text{ mA}$	3.0		0.4	
		$I_{OL} = 24 \text{ mA}$	3.0		0.55	
I_I	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.3 - 3.6		±5.0	μA
I_{OZ}	3-STATE Output Leakage	$0 \leq V_O \leq 5.5V$ $V_I = V_{IH} \text{ or } V_{IL}$	2.3 - 3.6		±5.0	μA
I_{OFF}	Power-Off Leakage Current	$V_I \text{ or } V_O = 5.5V$	0		10	μA

DC Electrical Characteristics (Continued)								
Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C		Units		
				Min	Max			
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	2.3 – 3.6		10	μA		
		3.6V ≤ V _I , V _O ≤ 5.5V (Note 5)	2.3 – 3.6		±10	μA		
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} - 0.6V	2.3 – 3.6		500	μA		
Note 5: Outputs disabled or 3-STATE only.								
AC Electrical Characteristics								
Symbol	Parameter	T _A = -40°C to +85°C, R _L = 500 Ω						Units
		V _{CC} = 3.3V ± 0.3V		V _{CC} = 2.7V		V _{CC} = 2.5 ± 0.2V		
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
		Min	Max	Min	Max	Min	Max	
f _{MAX}	Maximum Clock Frequency	150						MHz
t _{PHL}	Propagation Delay	1.5	8.5	1.5	9.5	1.5	10.5	ns
t _{PLH}	CP to O _n	1.5	8.5	1.5	9.5	1.5	10.5	
t _{PZL}	Output Enable Time	1.5	8.5	1.5	9.5	1.5	10.5	ns
t _{PZH}		1.5	8.5	1.5	9.5	1.5	10.5	
t _{PLZ}	Output Disable Time	1.5	6.5	1.5	7.0	1.5	7.8	ns
t _{PHZ}		1.5	6.5	1.5	7.0	1.5	7.8	
t _S	Setup Time	2.5		2.5		4.0		ns
t _H	Hold Time	1.5		1.5		2.0		ns
t _W	Pulse Width	3.3		3.3		4.0		ns
t _{OSSL}	Output to Output Skew (Note 6)		1.0					ns
t _{OSLH}			1.0					
Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t _{OSSL}) or LOW-to-HIGH (t _{OSLH}).								
Dynamic Switching Characteristics								
Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C		Units		
				Typical				
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	0.8		V		
		C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V	2.5	0.6				
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	-0.8		V		
		C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V	2.5	-0.6				
Capacitance								
Symbol	Parameter	Conditions	Typical	Units				
C _{IN}	Input Capacitance	V _{CC} = Open, V _I = 0V or V _{CC}	7	pF				
C _{OUT}	Output Capacitance	V _{CC} = 3.3V, V _I = 0V or V _{CC}	8	pF				
C _{PD}	Power Dissipation Capacitance	V _{CC} = 3.3V, V _I = 0V or V _{CC} , f = 10 MHz	25	pF				

AC LOADING and WAVEFORMS Generic for LCX Family

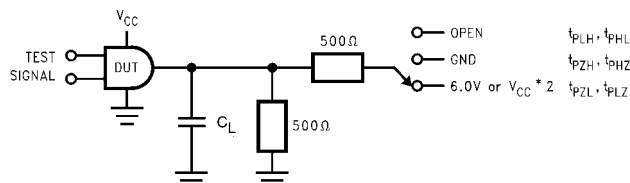
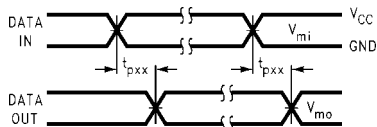
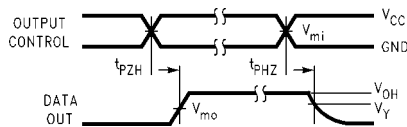


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

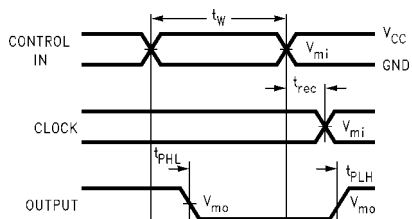
Test	Switch
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t_{PZH}, t_{PHZ}	GND



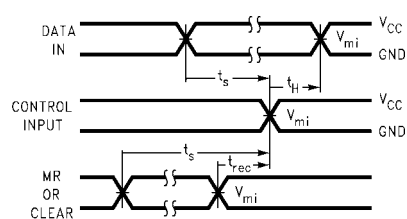
Waveform for Inverting and Non-Inverting Functions



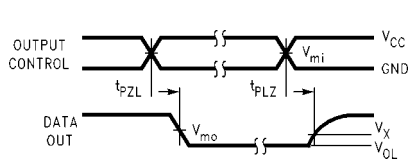
3-STATE Output High Enable and Disable Times for Logic



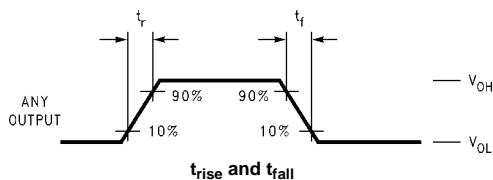
Propagation Delay, Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

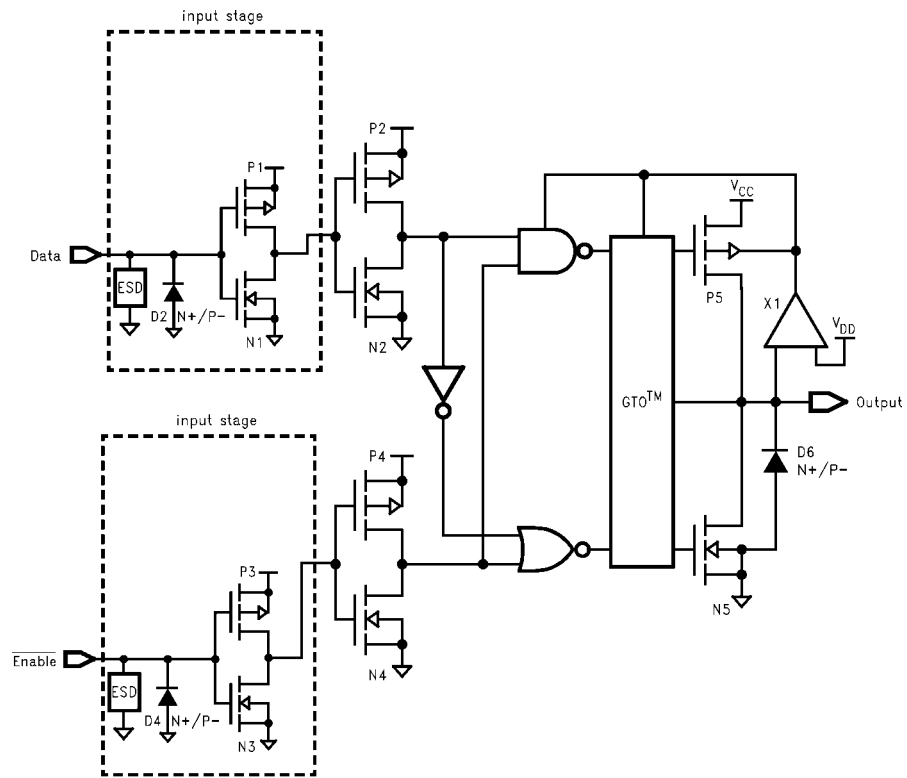


t_{rise} and t_{fall}

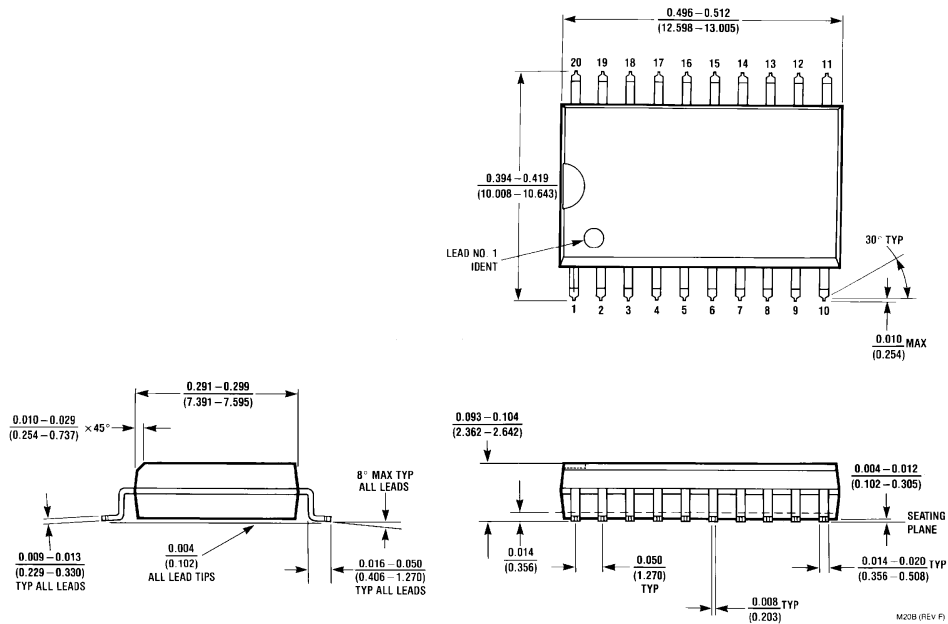
FIGURE 2. Waveforms
(Input Characteristics; $f = 1MHz, t_R = t_F = 3ns$)

Symbol	V_{CC}		
	$3.3V \pm 0.3V$	2.7V	$2.5V \pm 0.2V$
V_{mi}	1.5V	1.5V	$V_{CC}/2$
V_{mo}	1.5V	1.5V	$V_{CC}/2$
V_x	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
V_y	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

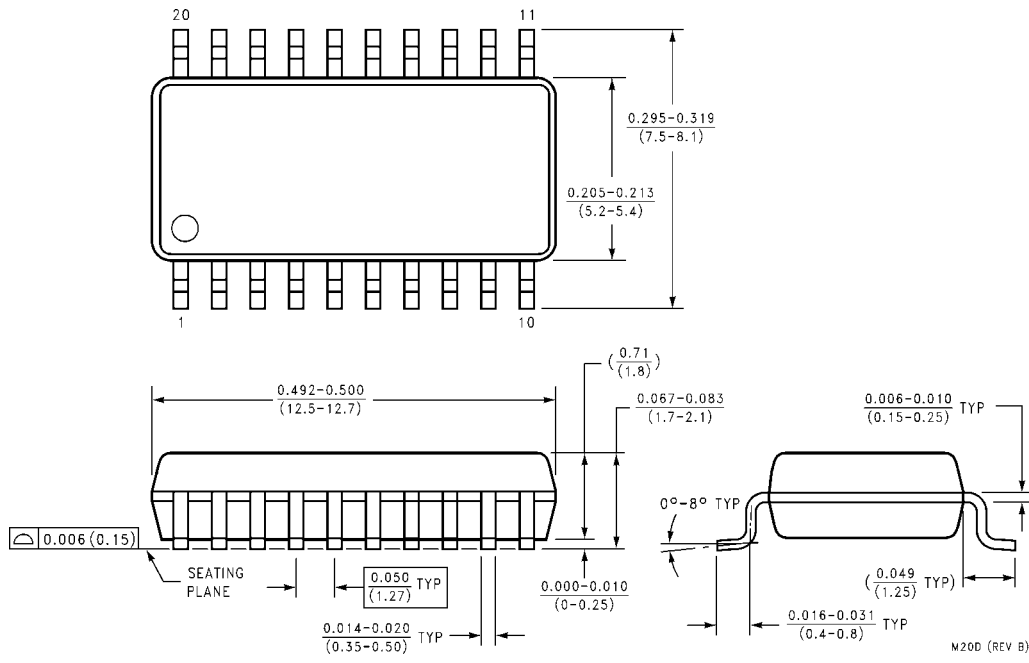
Schematic Diagram Generic for LCX Family



Physical Dimensions inches (millimeters) unless otherwise noted

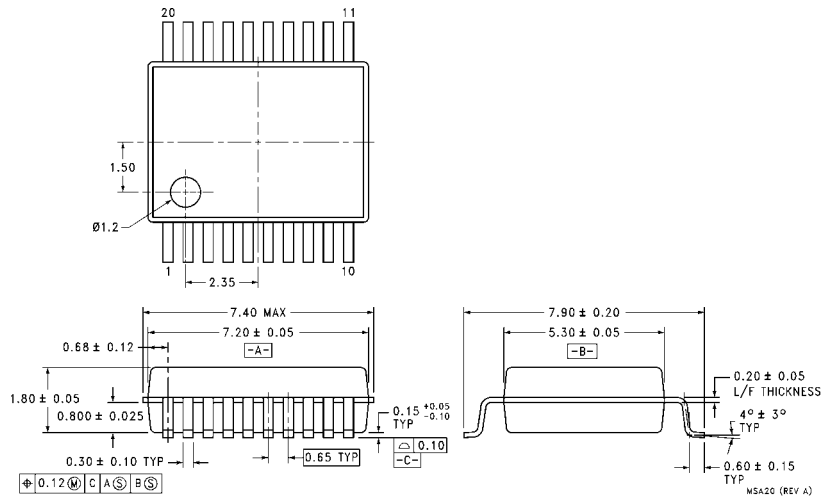


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B**



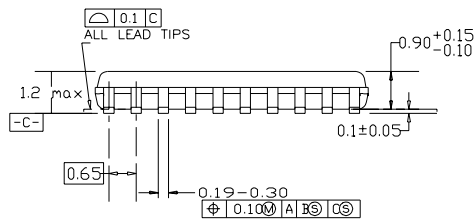
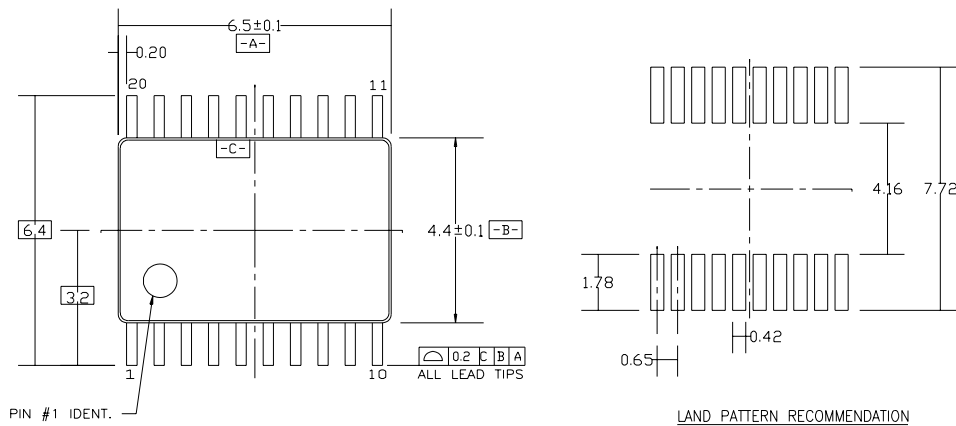
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20**

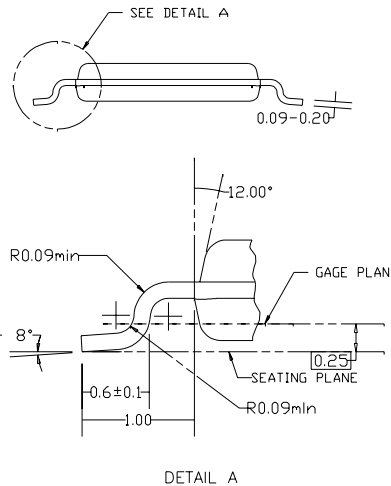
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.



20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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